



100V N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV _{DSS}	Rds(ON) Max	I _D Max Tc = +25°C
100V	9mΩ @ V _G S = 10V	90A
	13mΩ @ V _{GS} = 4.5V	76A

Description

This new generation MOSFET features low on-resistance and fast switching, making it ideal for high efficiency power management applications.

Applications

- Power Management Functions
- DC-DC Converters
- Backlighting

Features

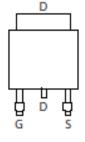
- 100% Unclamped Inductive Switching (UIS) Test in Production –
 Ensures More Reliable and Robust End Application
- Low Rds(ON) Minimizes Power Losses
- Low Q_q Minimizes Switching Losses
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please contact us or your local Diodes representative. https://www.diodes.com/quality/product-definitions/

Mechanical Data

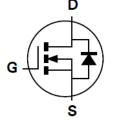
- Case: TO252
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Leadframe.
 Solderable per MIL-STD-202, Method 208 (€3)
- Weight: 0.33 grams (Approximate)



Top View



Pin Out Top View



Equivalent Circuit

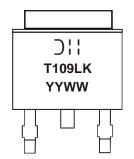
Ordering Information (Note 4)

Part Number	Case	Packaging
DMT10H009LK3-13	TO252 (DPAK)	2,500/Tape & Reel

Notes:

- 1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



Dill = Manufacturer's Marking
T109LK = Product Type Marking Code
YYWW = Date Code Marking
YY = Last Two Digits of Year (ex: 19 = 2019)
WW = Week Code (01 to 53)



Maximum Ratings $(@T_A = +25^{\circ}C, \text{ unless otherwise specified.})$

Characteristic	Symbol	Value	Unit	
Drain-Source Voltage		VDSS	100	V
Gate-Source Voltage		Vgss	±20	V
Continuous Drain Compart V 40V	Tc = +25°C	- I _D	90	A
Continuous Drain Current, V _{GS} = 10V	Tc = +70°C		73	
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)	I _{DM}	360	Α	
Maximum Continuous Body Diode Forward Current (Note 6)		Is	91	Α
Pulsed Body Diode Forward Current (10µs Pulse, Duty Cycle = 1%)		I _{SM}	360	А
Avalanche Current, L = 0.3mH		I _{AS}	21	А
Avalanche Energy, L = 0.3mH		Eas	66.2	mJ

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)		PD	1.7	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	Reja	71	°C/W
Total Power Dissipation (Note 6)		PD	3	W
Thermal Resistance, Junction to Ambient (Note 6) Steady State		$R_{\theta JA}$	40	°C/W
Thermal Resistance, Junction to Case		Rejc	1.1	C/VV
Operating and Storage Temperature Range		TJ, TSTG	-55 to +150	°C

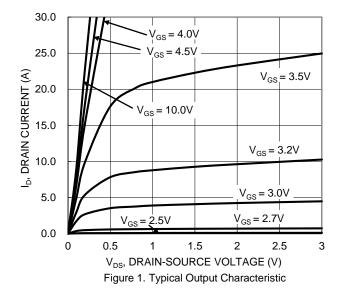
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

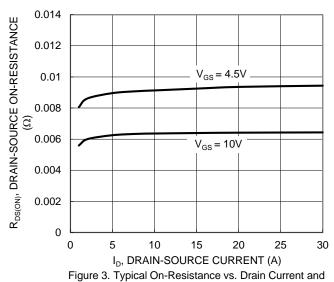
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BVDSS	100	_	_	V	$V_{GS} = 0V, I_D = 1mA$	
Zero Gate Voltage Drain Current	I _{DSS}	_	_	1	μΑ	$V_{DS} = 80V, V_{GS} = 0V$	
Gate-Source Leakage	Igss	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	Vgs(th)	1.2	_	2.5	V	$V_{DS} = V_{GS}$, $I_D = 250\mu A$	
Static Drain-Source On-Resistance	D-s/s/iii		6.7	9	mΩ	$V_{GS} = 10V, I_{D} = 20A$	
Static Dialii-Source Off-Resistance	R _{DS(ON)}	_	9.1	13	11177	$V_{GS} = 4.5V, I_{D} = 5A$	
Diode Forward Voltage	VsD	_	0.8	1.3	V	Vgs = 0V, Is = 20A	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	Ciss	_	2309	_		V _{DS} = 50V, V _{GS} = 0V f = 1MHz	
Output Capacitance	Coss	_	536	_	pF		
Reverse Transfer Capacitance	Crss	_	15.7	_			
Gate Resistance	Rg	_	1.9	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge	Qg	_	20	_		V 50V L 00A	
Gate-Source Charge	Qgs	_	7.0	_	nC	$V_{DD} = 50V, I_{D} = 20A,$	
Gate-Drain Charge	Q _{gd}	_	8.5	_		Vgs = 4.5V	
Turn-On Delay Time	tD(ON)	_	5.4	_			
Turn-On Rise Time	t _R	_	10.6	_		$V_{DD} = 50V, V_{GS} = 10V,$ $I_D = 20A, R_g = 3\Omega$	
Turn-Off Delay Time	t _{D(OFF)}	_	28.3	_	ns		
Turn-Off Fall Time	tF	_	14.9	_			
Reverse Recovery Time	trr	_	44.3	_	ns	1 200 4:/44 4000///-	
Reverse Recovery Charge	Q _{RR}	_	65.5	_	nC	I _F = 20A, di/dt = 100A/μs	

5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

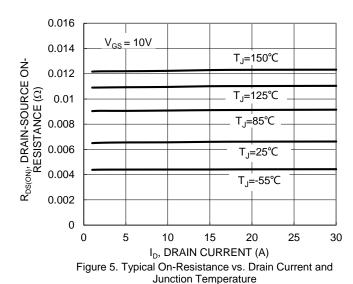
Device mounted on FR-4 substrate PC board, 2oz copper, with 1-inch square copper plate.
 Short duration pulse test used to minimize self-heating effect.
 Guaranteed by design. Not subject to product testing.

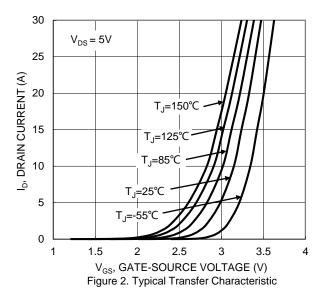


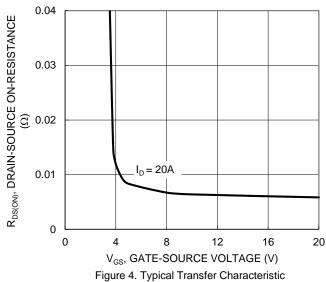


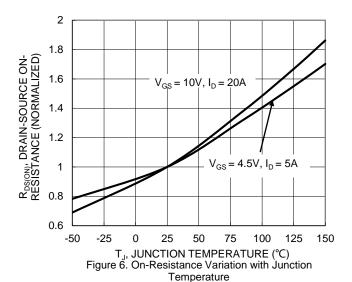


Gate Voltage











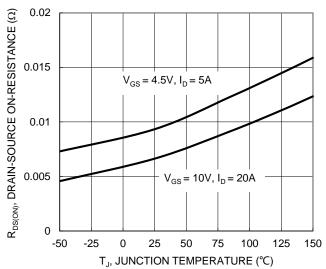


Figure 7. On-Resistance Variation with Junction Temperature

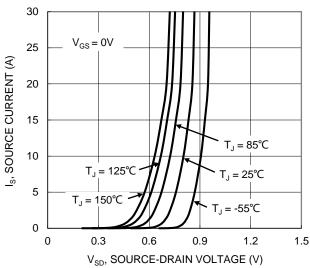


Figure 9. Diode Forward Voltage vs. Current

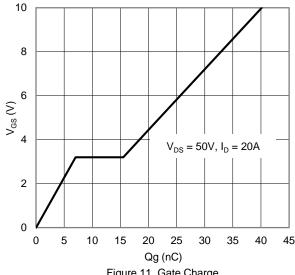


Figure 11. Gate Charge

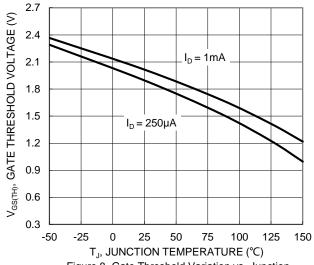


Figure 8. Gate Threshold Variation vs. Junction **Temperature**

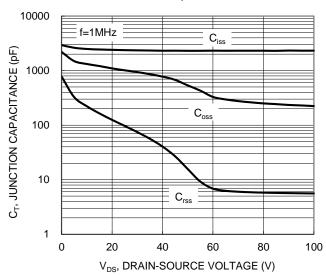
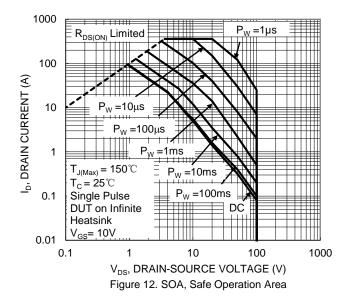


Figure 10. Typical Junction Capacitance





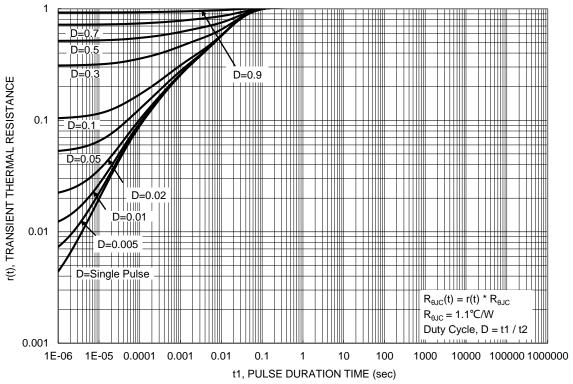


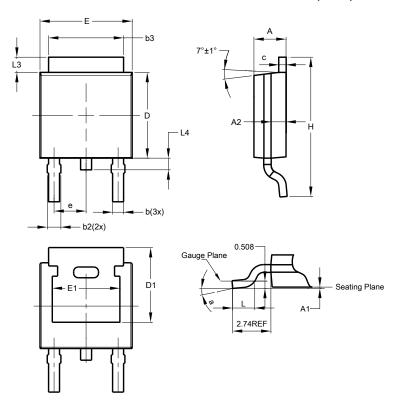
Figure 13. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

TO252 (DPAK)

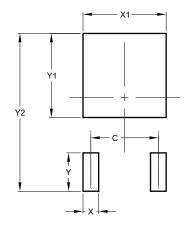


TO252 (DPAK)					
Dim	Min	Max	Тур		
Α	2.19	2.39	2.29		
A 1	0.00	0.13	0.08		
A2	0.97	1.17	1.07		
b	0.64	0.88	0.783		
b2	0.76	1.14	0.95		
b3	5.21	5.46	5.33		
С	0.45	0.58	0.531		
D	6.00	6.20	6.10		
D1	5.21				
е	-	-	2.286		
Е	6.45	6.70	6.58		
E1	4.32	-	-		
Н	9.40	10.41	9.91		
L	1.40	1.78	1.59		
L3	0.88	1.27	1.08		
L4	0.64	1.02	0.83		
а	0°	10°	-		
All Dimensions in mm					

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

TO252 (DPAK)



Dimensions	Value (in mm)
С	4.572
Х	1.060
X1	5.632
Y	2.600
Y1	5.700
Y2	10.700



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